TOIREX

XBS203V19R-G

ETR16035-002

Schottky Barrier Diode, 2A, 30V Type

■FEATURES

Forward Voltage : V_F=0.35V (TYP.)

Forward Current : $I_{F(AV)}$ =2A Repetitive Peak Reverse Voltage : V_{RM} =30V

■ABSOLUTE MAXIMUM RATINGS

Ta=25°0

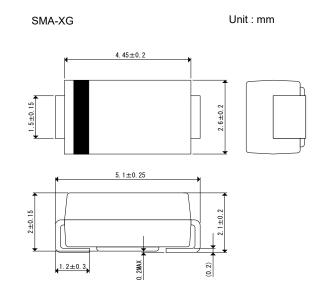
PARAMETER	SYMBOL	RATINGS	UNITS
Repetitive Peak Reverse Voltage	V_{RM}	30	V
Reverse Voltage	V _R	30	V
Forward Current (Average)	I _{F(AV)}	2	Α
Non Continuous Forward Surge Current(*1)	I _{FSM}	50	Α
Junction Temperature	Tj	125	°C
Storage Temperature Range	Tstg	-55~+150	°C

^(*1) Non continuous high amplitude 60Hz half-sine wave.

■APPLICATIONS

- Rectification
- Protection against reverse connection of battery

■ PACKAGING INFORMATION



■MARKING RULE



123456: 203V19(Product Number)

78 : Assembly Lot Number

■PRODUCT NAME

PRODUCT NAME	PACKAGE	ORDER UNIT
XBS203V19R-G(*1)	SMA-XG	2,000/Reel

^(*1) The "-G" suffix denotes Halogen and Antimony free as well as being fully EU RoHS compliant.

■ELECTRICAL CHARACTERISTICS

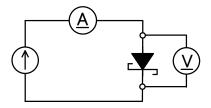
Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT
Forward Voltage	VF1	I _F =0.5A	-	0.28	0.365	V	1
	VF2	I _F =1A		0.305	0.375	V	1
	VF3	I _F =2A		0.35	0.39	V	1
Reverse Current	lr	V _R =30V	-	0.35	3	mA	2
Inter-Terminal Capacity	Ct	V _R =1V , f=1MHz	1	280	1	pF	3
Reverse Recovery Time	trr	I _F =I _R =10mA , irr=1mA	-	70		ns	4

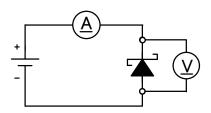
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■TEST CIRCUITS

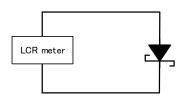
Circuit(1)



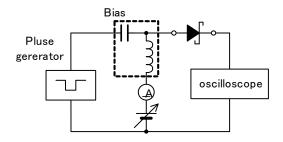
Circuit 2

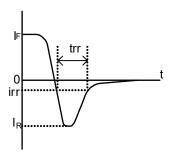


Circuit3



Circuit4



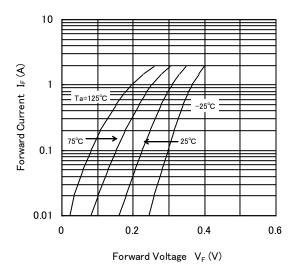


■NOTES ON USE

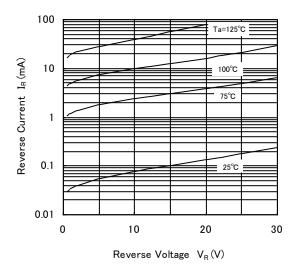
- 1) Please use this IC within the absolute maximum ratings.
- 2) Even within the ratings, in case of high load use continuously such as high temperature, high voltage, high current and thermal stress may cause reliability degradation of the IC. Adequate "Derating" should be taken into consideration while designing.
- 3) Torex places an importance on improving our products and their reliability. We request that users incorporate fail-safe designs and post-aging protection treatment when using Torex products in their systems.

■TYPICAL PERFORMANCE CHARACTERISTICS

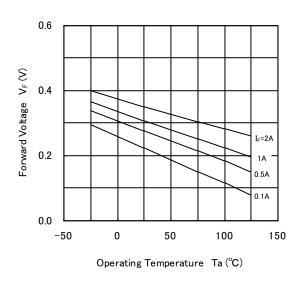
(1) Forward Current vs. Forward Voltage



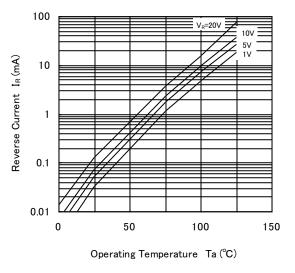
(2) Reverse Current vs. Reverse Voltage



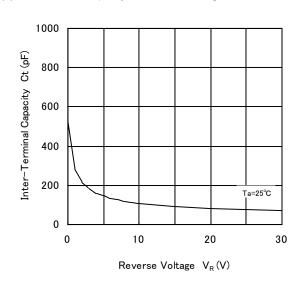
(3) Forward Voltage vs. Operating Temperature



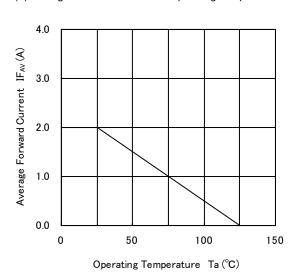
(4) Reverse Current vs. Operating Temperature



(5) Inter-Terminal Capacity vs. Reverse Voltage



(6) Average Forward Current vs. Operating Temperature



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■PACKAGING INFORMATION

For the latest package information go to, www.torexsemi.com/technical-support/packages

PACKAGE	OUTLINE / LAND PATTERN	THERMAL CHARACTERISTICS
SMA-XG	SMA-XG PKG	

- The product and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date.
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- 5. Although we make continuous efforts to improve the quality and reliability of our products; nevertheless Semiconductors are likely to fail with a certain probability. So in order to prevent personal injury and/or property damage resulting from such failure, customers are required to incorporate adequate safety measures in their designs, such as system fail safes, redundancy and fire prevention features.
- Our products are not designed to be Radiation-resistant.
- 7. Please use the product listed in this datasheet within the specified ranges.
- 8. We assume no responsibility for damage or loss due to abnormal use.
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